



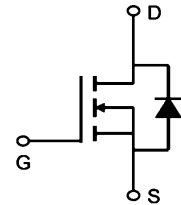
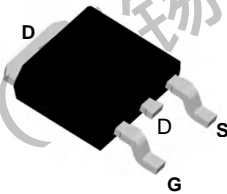
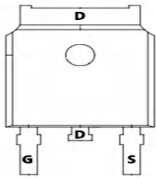
TMG120N085D

N-Channel Enhancement Mosfet

<p>General Description</p> <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>General Features</p> <p>$V_{DS} = 85V$ $I_D = 120A$ $R_{DS(ON)} = 4.5m\Omega (typ.) @ V_{GS} = 10V$</p> <p>100% UIS Tested 100% R_g Tested</p>
--	--



D:TO-252-3L



Marking: G120N085

Absolute Maximum Ratings ($T_C = 25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	85	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	120	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	84	A
I_{DM}	Pulsed Drain Current ²	465	A
EAS	Single Pulse Avalanche Energy ³	338	mJ
P_D	Total Power Dissipation ³	208	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	62	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	6.6	$^\circ C/W$

TMG120N085D

N-Channel Enhancement Mosfet

Electrical Characteristics at Tc=25°C unless otherwise specified

Characteristics	Test Condition	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = 0 V, I_D = 250 \mu A$	BV_{DSS}	85	-	-	V
Drain-Source Leakage Current	$V_{DS} = 80 V, V_{GS} = 0 V$	I_{DSS}	-	-	1	μA
Gate Leakage Current	$V_{GS} = \pm 20 V, V_{DS} = 0 V$	I_{GSS}	-	-	± 100	nA
Gate-Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	$V_{GS(th)}$	2	3	4	V
Drain-Source On-State Resistance (Note 3)	$V_{GS} = 10 V, I_D = 20 A$	$R_{DS(on)}$	-	4.5	5.0	m Ω
Forward Transconductance	$V_{DS} = 5 V, I_D = 20 A$	gfs	-	31	-	S
Gate Resistance	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$	RG	-	1.9	-	Ω
Input Capacitance	$V_{DS} = 40 V, V_{GS} = 0V, f = 1MHz$	C_{iss}	-	3365	-	pF
Output Capacitance		C_{oss}	-	1264	-	pF
Reverse Transfer Capacitance		C_{rss}	-	46	-	pF
Turn-on Delay Time(Note2)	$V_{GS} = 10V, V_{DS} = 40V$ $RL = 2.0\Omega, R_{GEN} = 3\Omega$	$t_{d(ON)}$	-	17.6	-	ns
Rise Time(Note2)		t_r	-	27	-	ns
Turn-Off Delay Time(Note2)		$t_{d(OFF)}$	-	31	-	ns
Fall Time(Note2)		t_f	-	10.8	-	ns
Total Gate Charge(Note2)	$V_{DS} = 40V, V_{GS} = 10V, I_D = 20A$	Q_G	-	56	-	nC
Gate to Source Charge(Note2)		Q_{GS}	-	18.3	-	nC
Gate to Drain Charge(Note2)		Q_{GD}	-	15	-	nC

Source-Drain Diode Characteristics at Ta=25°C unless otherwise specified

Characteristics	Test Condition	Symbo	Min.	Typ.	Max.	Unit
Maximun Body-Diode Continuous Current		I_S	-	-	120	A
Drain-Source Diode Forward Voltage	$V_{GS} = 0V, I_S = 1A, T_J = 25^\circ C$	V_{SD}	-	0.7	1.0	V
Reverse Recovery Time(Note2)	$T_J = 25^\circ C, I_F = 20A$ $di / dt = 100 A/\mu s$	trr	-	58	-	ns
Reverse Recovery Charge(Note2)		Qrr	-	95	-	nC

Note2:Pulse test: 300 μs pulse width, 2 % duty cycle



TMG120N085D

N-Channel Enhancement Mosfet

RATINGS AND CHARACTERISTIC CURVES

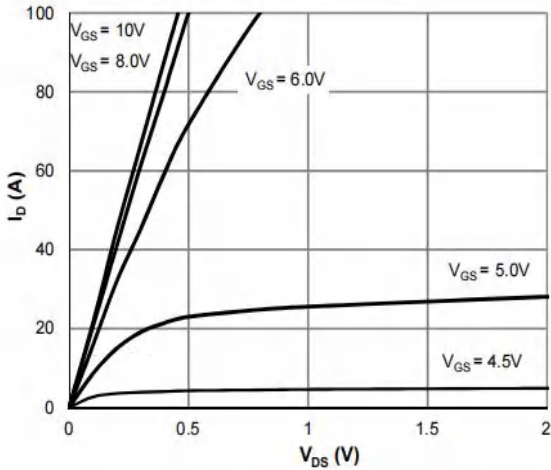


Figure 1: Saturation Characteristics

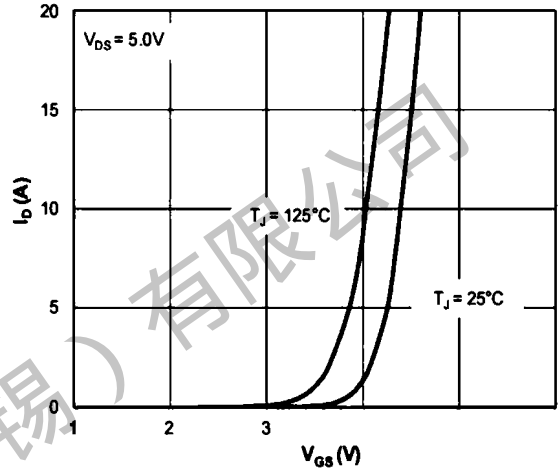


Figure 2: Transfer Characteristics

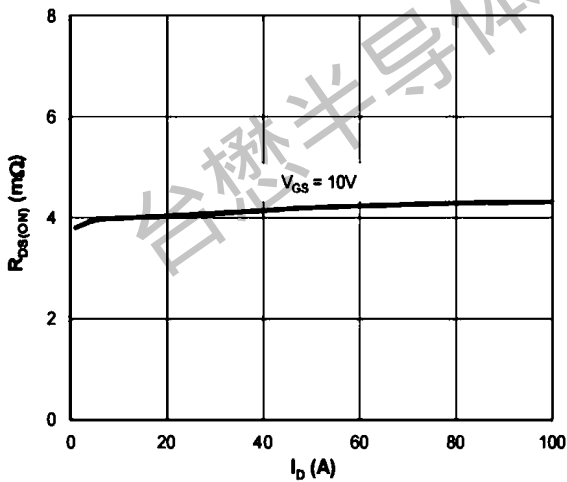


Figure 3: $R_{DS(ON)}$ vs. Drain Current

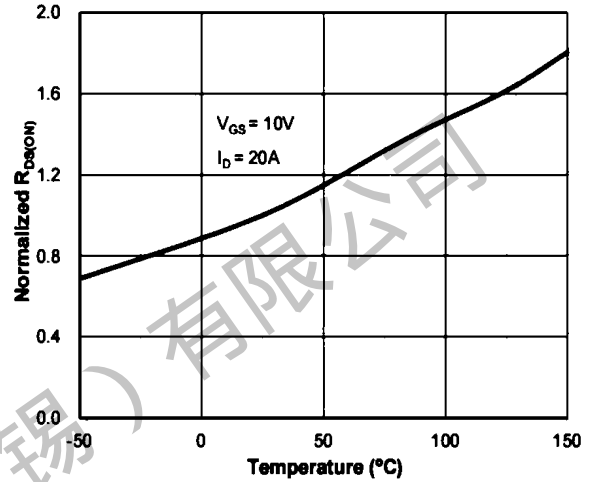


Figure 4: $R_{DS(ON)}$ vs. Junction Temperature

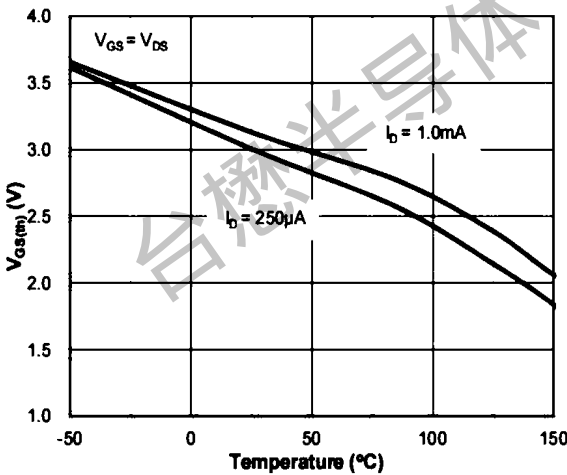


Figure 5: $V_{GS(th)}$ vs. Junction Temperature

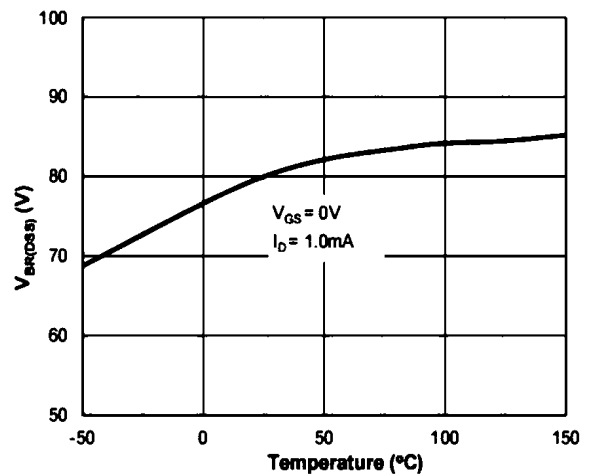


Figure 6: $V_{BR(DSS)}$ vs. Junction Temperature

TMG120N085D

N-Channel Enhancement Mosfet

RATINGS AND CHARACTERISTIC CURVES

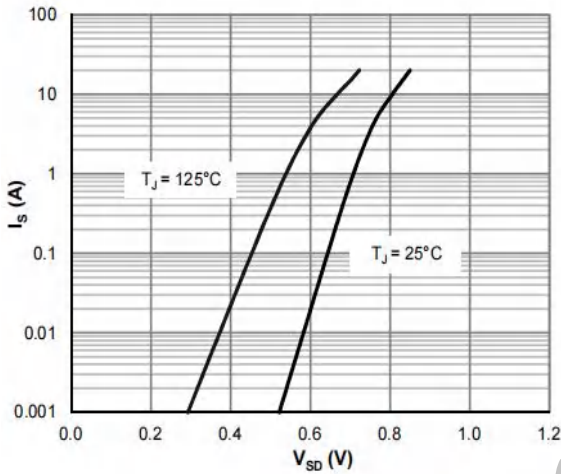


Figure 7: Body-Diode Characteristics

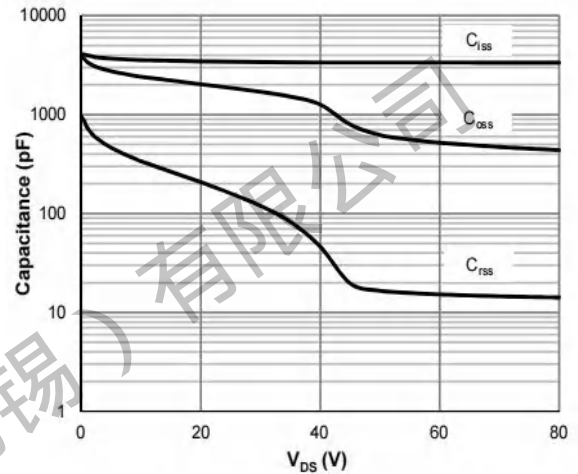


Figure 8: Capacitance Characteristics

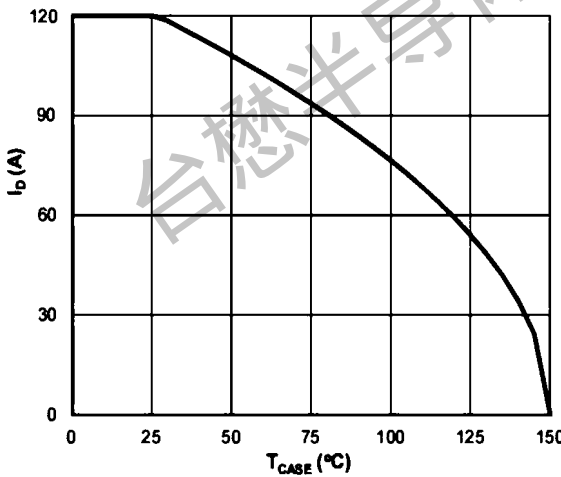


Figure 9: Current De-rating

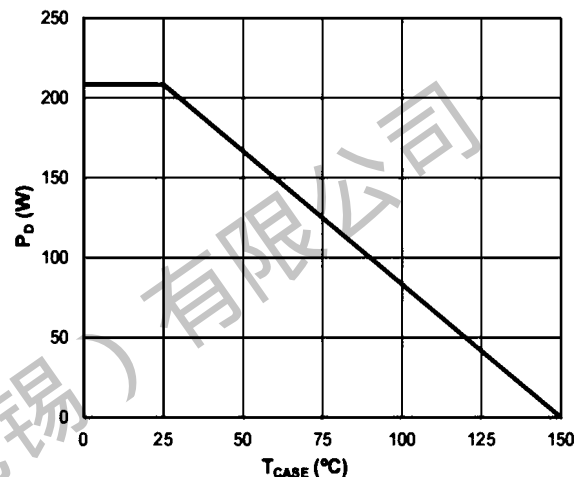


Figure 10: Power De-rating

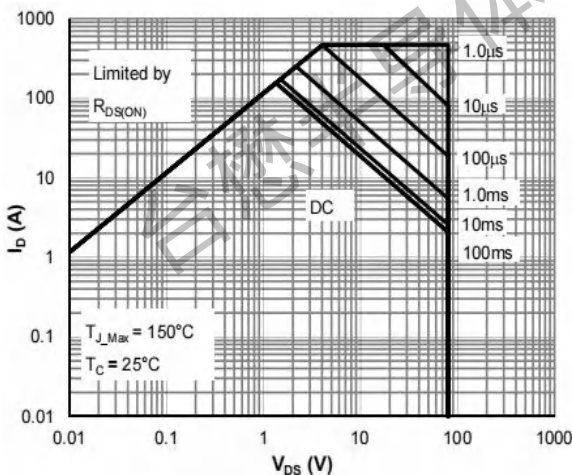


Figure 11: Maximum Safe Operating Area

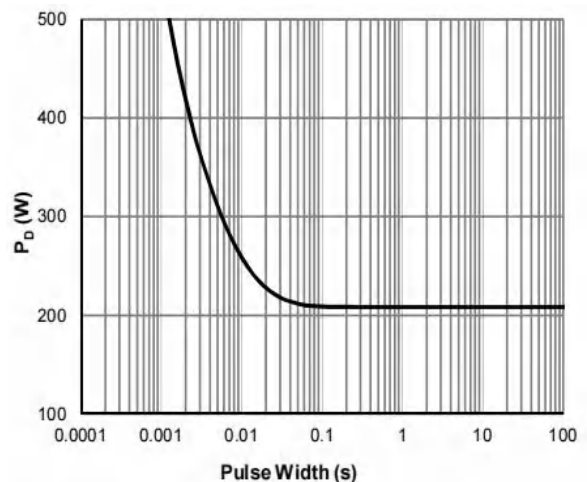
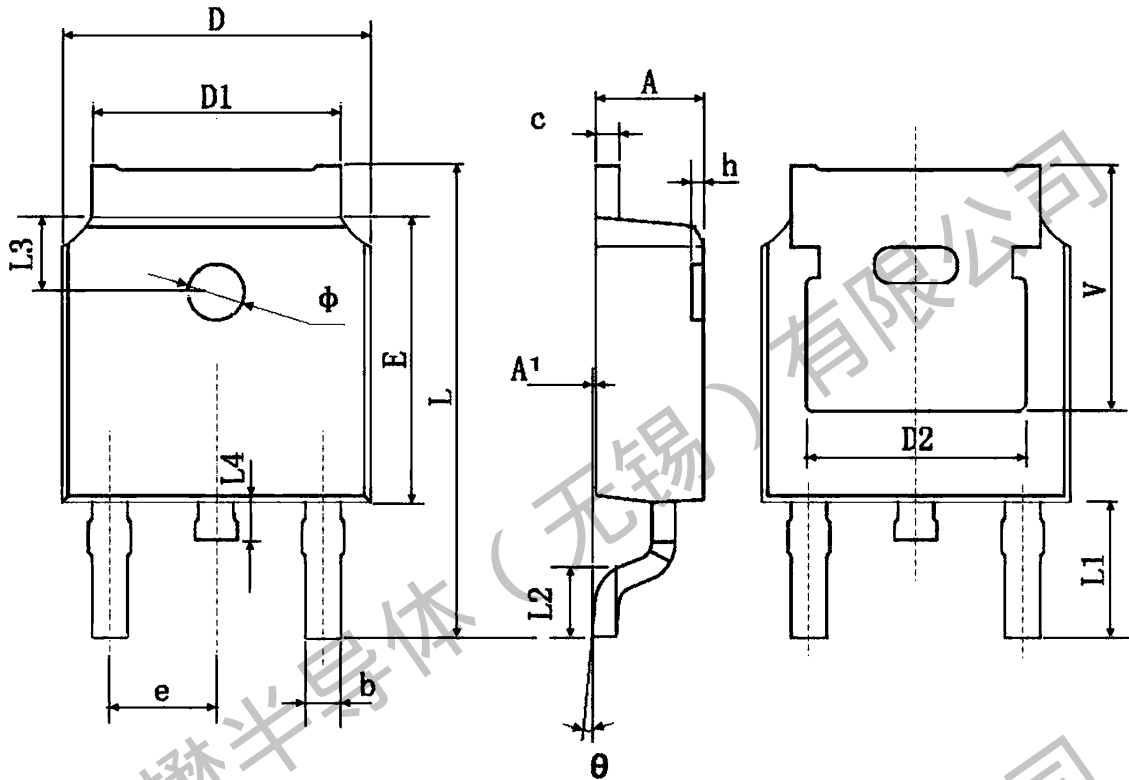


Figure 12: Single Pulse Power Rating, Junction-to-Case

TMG120N085D

N-Channel Enhancement Mosfet

Package Mechanical Data: TO-252-3L

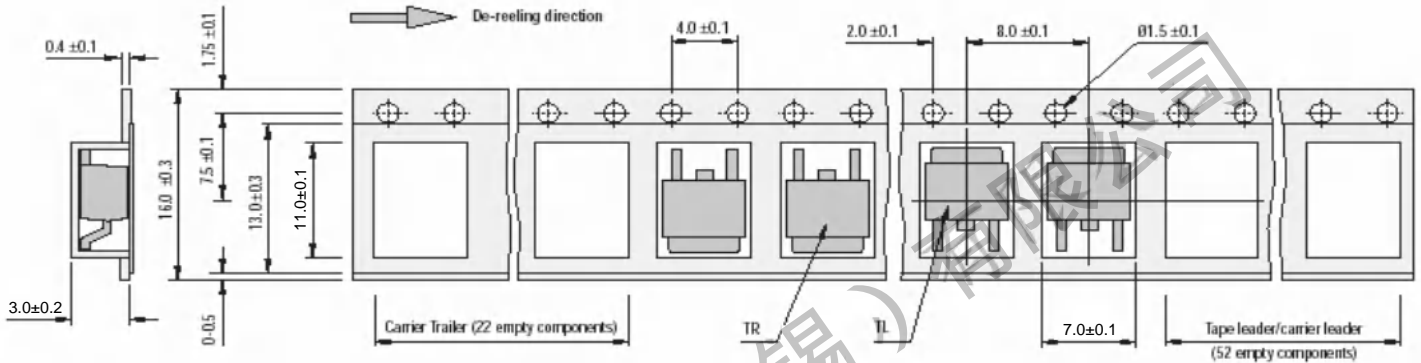


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
phi	1.100	1.300	0.043	0.051
theta	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
v	5.350 TYP.		0.211 TYP.	

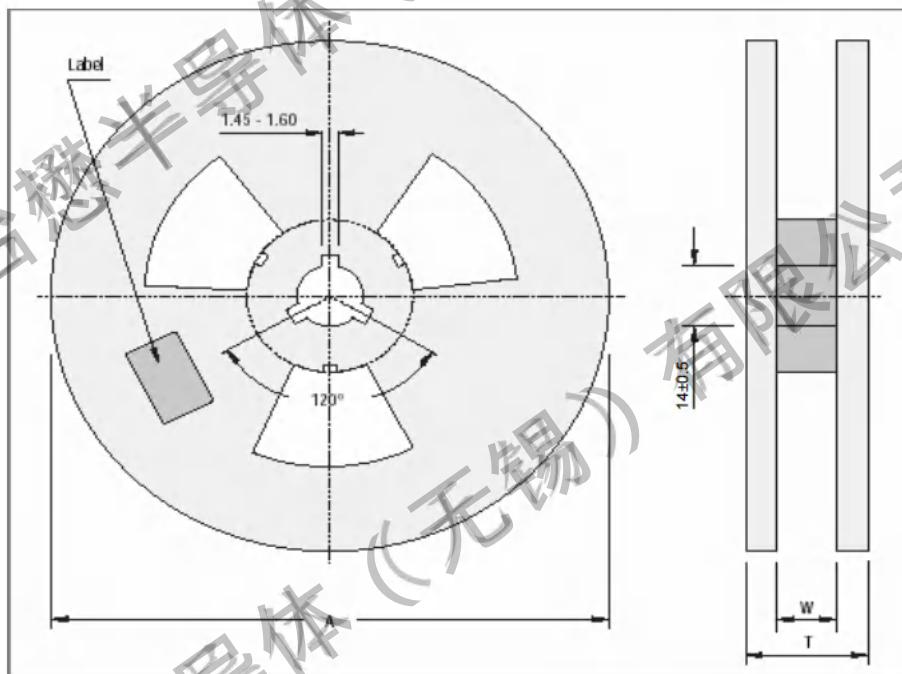
TMG120N085D

N-Channel Enhancement Mosfet

TO-252-3L Embossed Carrier Tape



TO-252-3L Reel



All Dimensions are in mm.

Reel Specifications				
Package	Tape Width	Reel Dia. A - Max	Inside Thickness W	Reel Thickness T - max
TO-252-3L	16	330	18.0 ±1.5	20

Packaging Information

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
2,500 pcs	13 inch	5,000 pcs	355×370×50	25,000 pcs	380×275×380	



Important Notices and Disclaimers

- Tritech-MOS Technology Corp.reserves the right to change thisdocument, its products, and specifications at any time without prior notice.
- Before final design, purchase, or use, customers should obtain and confirm the latest product information and specifications.
- Tritech-MOS Technology Corp. makes no warranties, representations or warranties regarding the suitability of its products for any specific purpose, and Tritech-MOS Technology Corp. does not assume any responsibility for application assistance or customer product design.
- Tritech-MOS Technology Corp. does not guarantee or assume any responsibility for the purchase or use of any unexpected or unauthorized products.
- Any intellectual property rights of Tritech-MOS Technology Corp. are not licensed through implicate or other means.
- Products of Tritech-MOS Technology Corp. are not included as critical components in life support equipment or systems without explicit written approval from Tritech-MOS Technology Corp.

Revision history:

Date	Rev	Description	Page
2024.06.14	24.06	Original	